

The definitive guide to today's thin-film technologies

THIN-FILM DEPOSITION

PRINCIPLES & PRACTICE

The field of thin-film deposition is expanding rapidly, with applications ranging from razor-blade coatings to quantum-well lasers. Scientists, engineers, and technicians working with thin films all need a solid grounding in the basic principles underlying the various deposition techniques in order to best apply these tools and understand new developments.

This easy-to-read and well-illustrated text meets this need. Written by a seasoned researcher with unusually broad experience, the book covers deposition of thin films using all of the vapor-phase techniques. In addition to the fundamentals, it provides up-to-date coverage of evolving thin-film topics such as oil-free vacuum, microstructure control, lattice-matched heteroepitaxy, selective CVD, energetic condensation, high-density plasmas, and microanalysis. You'll find here the information you need to:

- Decipher the primary literature
- Select the best thin-film technique for a specific application
- Help predict and optimize deposition process behavior
- Investigate and solve production problems

Logical organization, consistent use of SI units, a complete list of symbols and acronyms, and an extensive index combine to make it easy to access and apply the wealth of information in this essential reference.

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